

Gap Pad

Product Name	Description	Key Attributes	Thermal Conductivity (W/m•K)	Modulus at 25°C (kPa)	Dielectric Breakdown Voltage	Thickness (mm)	Flammability Rating
BERGQUIST GAP PAD 1000SF	Silicone-free, thermally conductive gap filling material	 No silicone outgassing No silicone extraction Reduced tack on one side to aid in application assembly Electrically isolating 	0.9	234	6,000 V at 250 μm	• 0.254 - 3.175	UL 94 V-1
BERGQUIST GAP PAD 2200SF	Silicone-free, thermally conductive gap filling material	Medium compliance with easy handlingElectrically isolating	2	228	5,000 V at 250 μm	• 0.254 – 3.175	UL 94 V-0
BERGQUIST GAP PAD 2202SF	Silicone- free, high performance, thermally conductive gap filling material	 Minimal compression set 12.7 μm film provides tack-free surface Tacky side allows for ease of handling and placement 	2	1,500	5,000 V at 250 µm	• 0.254 – 3.175	UL 94 V-0
BERGQUIST GAP PAD 3004SF	Silicone- free, high performance, thermally conductive gap filling material	 Excellent thermal performance 6.4 μm polyethylene terephthalate (PET) provides easy disassembly, leaving no residue Tacky side allows for ease of handling and placement 	3	2,450	6,000 V at 250 µm	• 0.254 – 3.175	UL 94 V-0
BERGQUIST GAP PAD HC3.0	Thermally conductive gap filling material	 High-compliance, low compression stress Fiberglass reinforced for shear and tear resistance Low modulus 	3	110	5,000 V at 500 µm	• 0.508 - 3.175	UL 94 V-0
BERGQUIST GAP PAD HC5.0	Thermally conductive gap filling material	 Highly conformable Exceptional thermal performance High-compliance, low compression stress Fiberglass reinforced for shear and tear resistance Low modulus 	5	121	5,000 V at 500 μm	 0.508 1.016 1.524 2.032 2.540 3.175 	UL 94 V-0
BERGQUIST GAP PAD VO ULTRA SOFT	Thermally conductive gap filling material	 Highly conformable, low hardness "Gel-like" modulus Decreased strain Puncture, shear and tear resistant Electrically isolating 	1	55	6,000 V at 500 µm	• 0.508 – 6.350	UL 94 V-0

Henkel AG & Co. KGaA Henkelstraße 67 40589 Düsseldorf | Germany Phone: +1 952 486 6313 E-mail: electronics@henkel.com www.henkel-adhesives.com/electronics



The information provided herein, especially recommendations for the usage and the application of our products, is based upon our knowledge and experience. Due to different materials used as well as to varying working conditions beyond our control we strictly recommend to carry out intensive trials to test the suitability of our products with regard to the required processes and applications. We do not accept any liability with regard to the above information or with regard to the above information is protected by copyright. In particular, any reproductions, adaptations, storage and processing in other media, including storage or processing by electronic means, enjoy copyright protection. Any exploitation in whole or in part thereof shall require the prior written consent of Henkel AG & Co. KGaA. Except as otherwise noted, all marks used in this document are trademarks and/or registered trademarks of Henkel and/or its affiliates in the US, Germany, and elsewhere. © Henkel AG & Co. KGaA, oz/2018